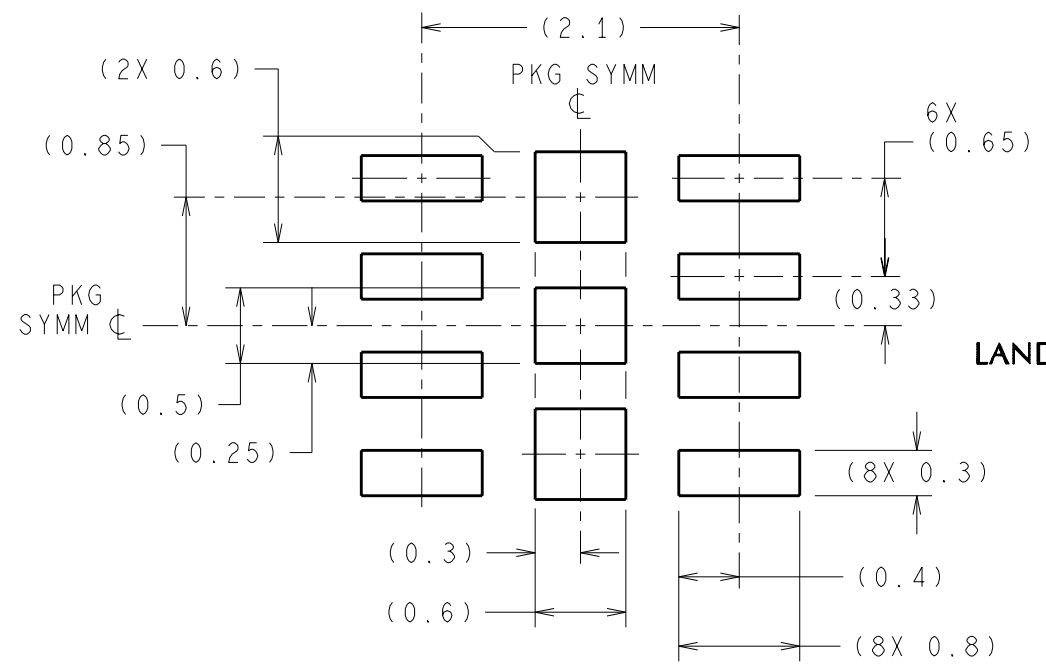
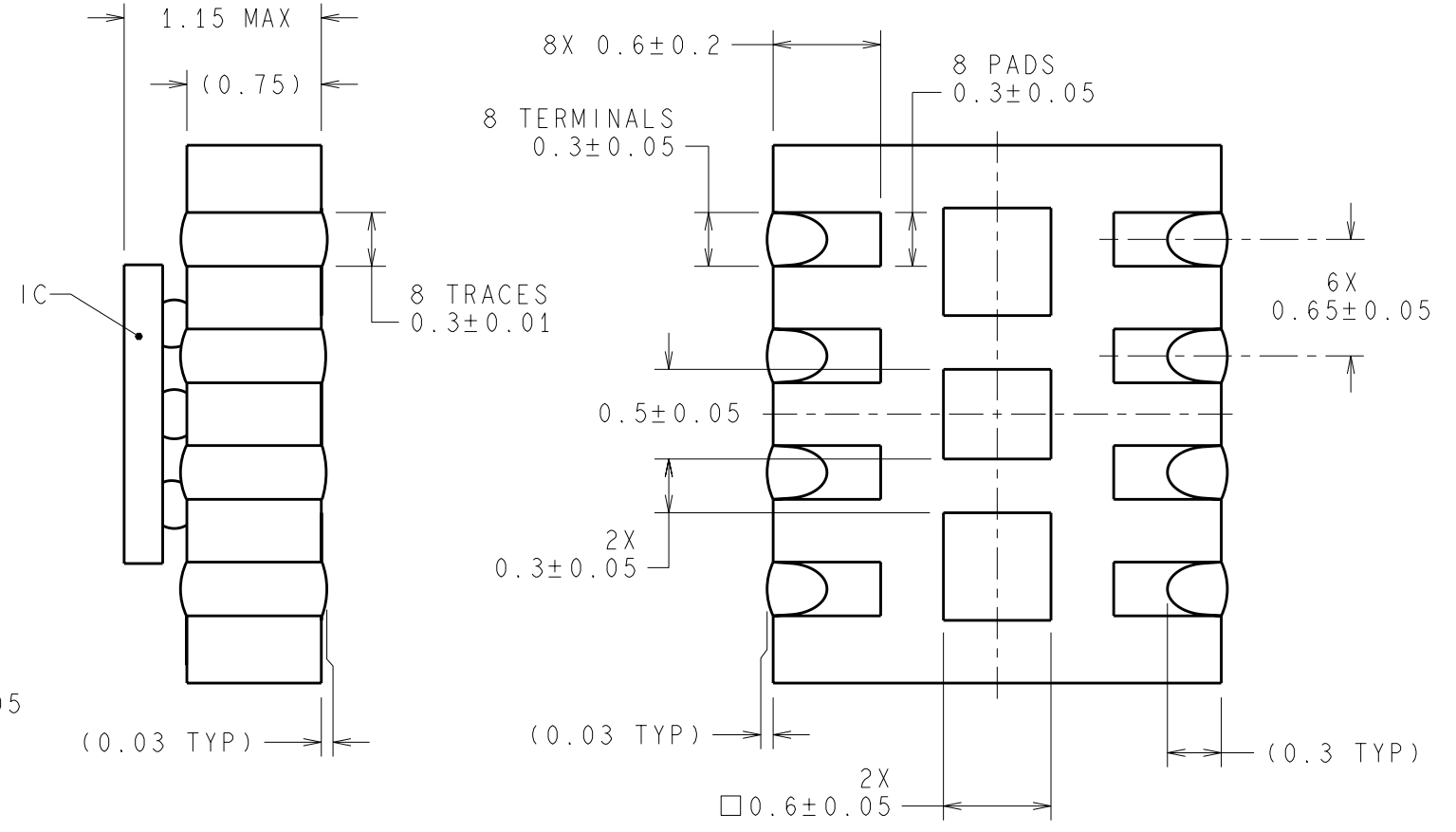
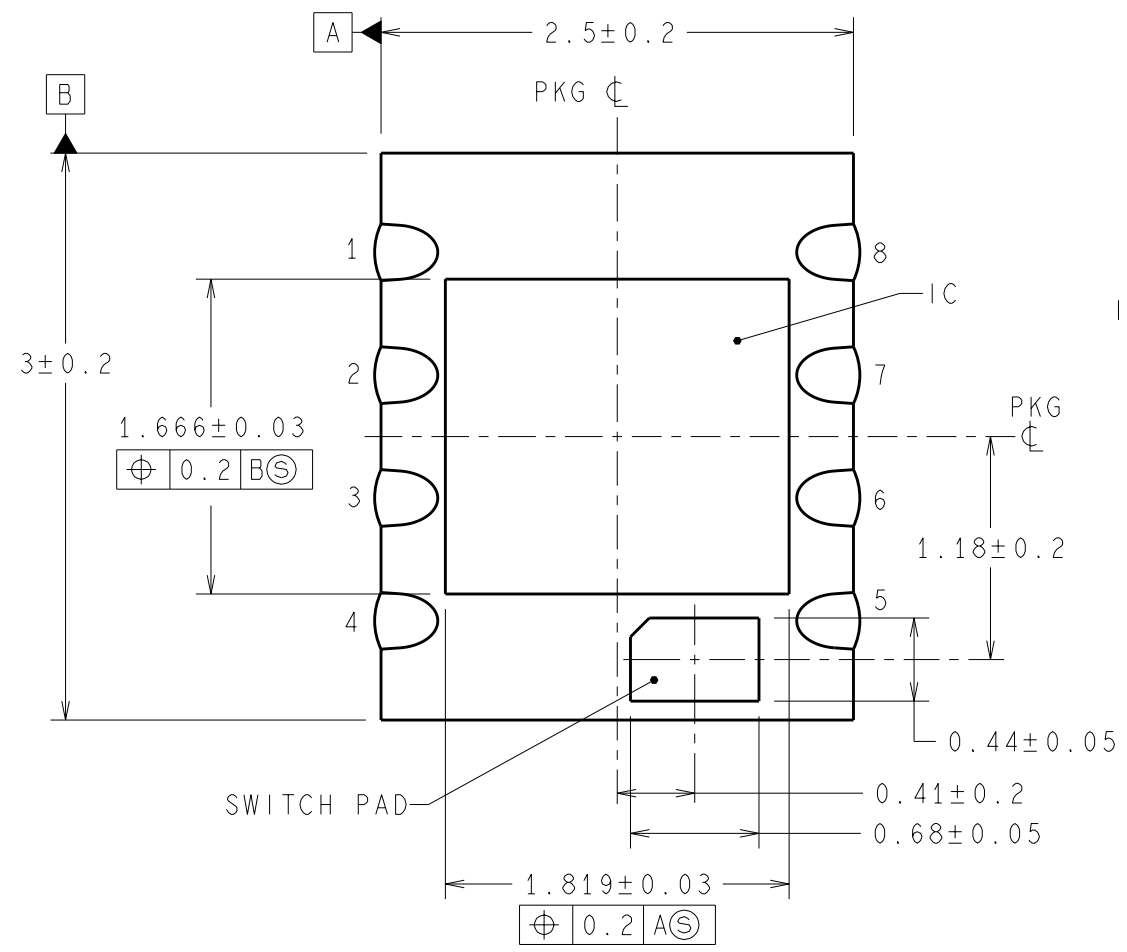


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	2312	06/06/2007	MS/JS
B	CHANGE IC LOCATION TO THE CENTER OF MODULE; RENUMBER PADS STARTING FROM THE TOP LEFT CORNER; ADD ICE BALL LENGT DIM (0.3); TERMINALS TOL $\pm 0.05$ WAS $\pm 0.1$ ; ADD TRACE DIM 8X 0.3 $\pm 0.1$ ; ADD VERT METAL TRACE WIDTH 0.3 $\pm 0.1$ ; IC SIZE 1.565x1.565 WAS 1.781x1.628; UPDATE NOTE 3.	2391	09/04/2007	MS/HN
C	CHANGE DIE SIZE FROM 1.565x1.565 mm TO 1.819x1.666 mm.	2530	05/28/2008	MS/TL/EL
D	CHANGE TOTAL PKG THICKNESS FROM 1.2 MAX TO 1.15 MAX	2644	12/01/2008	EL/TL/TK



**LAND PATTERN RECOMMENDATION**

**DIMENSIONS ARE IN MILLIMETERS**  
DIMENSIONS IN ( ) FOR REFERENCE ONLY



NOTES: UNLESS OTHERWISE SPECIFIED

1. RECOMMEND NON-SOLDER MASK DEFINED LANDING PAD.
2. MICRO SMD ON LTCC.
3. NO JEDEC REGISTRATION AS OF DECEMBER 2008.

APPROVALS		DATE	 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	MARTA SUCHY	06/06/2007		
DFTG. CHK.	THANH LEQUANG	12/01/2008	<b>PACKAGE ON SUBSTRATE,</b> <b>2.5x3x1.15mm, 8 PAD,</b> <b>0.65mm PITCH</b>	
ENGR. CHK.	EUGENE LEE	12/01/2008		
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
 MM	NTS	B	(SC)MKT-SE08A	D
FORMERLY: N/A			SHEET 1 of 1	